

Form 1449*		Docket Number: 1023-292US01	Application Number: 10/693,015
<b>INFORMATION DISCLOSURE STATEMENT IN AN APPLICATION</b> <small>(Use several sheets if necessary)</small>		Applicant: William C. Phillips; Alex C. Toy; Charles R. Lewis, Jr.; Mark E. Schommer; John W. Forsberg; David P. Olson	
		Filing Date: October 24, 2003	Group Art Unit: 3762
		Examiner Name: Tammie K. Heller	

**U.S. PATENT DOCUMENTS**

Examiner Initial	Document Number	Issue/Document Publication Date	Name	Filing Date If Appropriate
TKA	2003/0171789	09/11/2003	Malek et al.	
	6,622,031	09/16/2003	McCleary et al.	
	6,636,769	10/21/2003	Govari et al.	
	6,654,642	11/25/2003	North et al.	
	6,658,300	12/02/2003	Govari et al.	
	2004/0059395	03/25/2004	North et al.	
	2004/0100450	05/27/2004	Choi	
	2004/0106860	06/03/2004	Say et al.	
	2004/0106967	06/03/2004	Von Arx et al.	
	2004/0152953	08/05/2004	Goedeke	
	2004/0230247	11/18/2004	Stein et al.	
	2005/0075688	04/07/2005	Toy et al.	
	2005/0075692	04/07/2005	Schommer et al.	
TKA	6,930,602	08/16/2005	Dougherty et al.	VILLASECA ET AL.

**FOREIGN PATENT DOCUMENTS**

Examiner Initial	Document Number	Publication Date	Country	Translation	
				Yes	No
TKA	1 297 206	03/10/1992	Canada		
	2000322244	11/24/2000	Japan	Abstract	
	1 216 655	06/26/2002	Europe		
	WO 2002/057994	07/25/2002	PCT		
	WO 2003/008014	01/30/2003	PCT		
TKA	203 10 991 U1	01/15/2004	Germany		X

**OTHER DOCUMENTS** (Including Authors, Title of Item, Page(s), Vol/Issue No., Publisher, Place of Publication)

TKA	Crawford et al., "High-Frequency Microinductors with Amorphous Magnetic Ground Planes," IEEE Transactions of Magnetics, Vol. 38, No. 5, pp. 3168-3170, 2002.
TKA	"Copper/Polyester Laminate as an EMI/ESD Shield," IBM Technical Disclosure Bulletin, Vol. 28, No. 10, pp. 4342-4343, 1986.

<b>EXAMINER</b>	Date Considered
<i>Tammie Heller</i>	Jan-24 2006

\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.